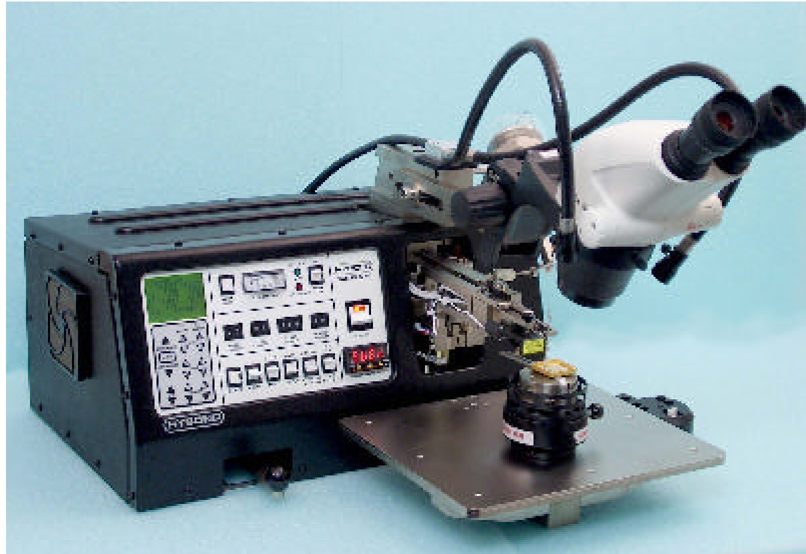
HYBOND

Soft Touch™

MODEL 626 MULTIPURPOSE DIGITAL THERMOSONIC WIRE BONDER

Ball Bonder, Wedge Bonder, Bump Bonder, Peg Bonder and more.



STANDARD FEATURES:

- Motorized Z control in auto and manual modes (fast & slow speeds for manual).
- 100 bond schedules programmable in non-volatile memory.
- Selectable/adjustable Reset Heights (Constant or Adaptive).
- 1-2-2 auto stitch or manual continuous stitch in manual & auto modes when ball bonding.
- Sensor bond actuation for variable bond height bonding.
- Audio and visual bond indicators.
- Static dissipative enclosure.
- 0.740 inch max. vertical bonding window.
- Vertical deep access of 0.53 inch when using 0.750 inch Capillary.
- Horizontal reach of 6.5 inches.
- Programmable loop and search heights.
- Built-in digital temperature controller.
- High/low power PLL ultrasonic generator.
- Swing away wire/ribbon clamps.
- 2 inch and 0.5 inch inertial spool holders.
- Z control by foot-switches or manipulator.
- **Ball, Wedge, Bump or Peg bond capable.**
- Electronic ball size control 0-4x wire diam.

Model 626 is a Deep Access, Long Reach Wire Bonder that **can operate as a Ball, Wedge, Bump or Peg bonder**. The 626 can be used for wire diameters from 0.7 to 2.0 mil (18 to 51µm) gold wire when in ball bonder configuration or 0.5 to 3.0 mil (12 to 76µm) and ribbon up to 1.0 x 12.0 mil (25 x 300µm) when in wedge or Peg bonding mode. The 626 was specifically designed for applications that require bonding at extreme height differences between 1st and 2nd bond and for bonding wires to sensitive devices such as gallium arsenide FET's and LED's. Model 626's motorized wire feed and wire/ribbon clamping system provide superior wire/ribbon control and allow the operator to increase or decrease tail length in 1 mil (25µm) increments at a touch of a switch. 626 shows actual units for set up of bond parameters. Change over from Ball bonder to Wedge bonder requires only a press of a button to turn EFO power to zero and a change from capillary to wedge tool. 626 can also operate in Bump or Peg bonding modes. Add OP-47 for pick, place and bond feature.

Partial List of Available Options:

! OP-06S6: Leica Stereo Zoom Microscope.
! OP-06A: Nikon SMZ-660 Microscope.
! OP-08A: Dual Fiber Optic Illuminator.
! OP-30A: 8:1 X-Y Manipulator.
! OP-31: Tool Heater and Temp. Controller.
! OP-82: Heated Transducer for Tool Heat.
! WST-15A: Heated Work Stage, 2.125 in. Top.
! WST-19A: Heated Work Stage, 4 x 6 in. Top.
! WST-65: Heated Work Stage, 10 x 6 in.Top.
! Wire and Ball tool as ordered per application.

Specifications for Model 626:

! Ultrasonic (U/S) System:	PLL self tuning.62.5KHz (nominal) system (±2.5KHz).
! U/S Power Range:	0-0.2 Watt on low setting and 0-2 Watts on high setting.
! Bond Time Range:	0mSec. to 900mSec.
! Bond Force Range:	12gr. to 250gr.
! Temperature control Range:	Ambient to 250 degrees Celsius.
! Bondable Wire Diameters:	0.5 to 3.0 mil (12,7 to 75Fm) diameter.
! Bondable Ribbon Dimensions:	Up to 1x20mil (25,4 x 510Fm) in Wedge bonder mode.
! Bondable Wire/Ribbon Materials:	Gold (aluminum and gold coated copper for wedge bonder).
! Bond head movement:	Motorized (servo). Activated by manipulator mounted switches or foot switches.
! Bond actuation:	By sensor at bond surface contact.
! Z Travel/Vertical Bonding Window:	0.750in. (1,90cm)/0.740in. (1,87cm)
! Table Motion:	4:1, manual.
! Input Power Requirements:	90 - 260VAC 50/60Hz @ 10A max.
! Minimum Bench Space Required:	20.0 x 25.0 in. (50,8 x 63,5cm).
! Unit Weight/Shipping Weight:	70lbs (31,8Kg)/150lbs (68,2Kg). Shipping weight may vary.
! Industry Standards:	CE.

For more information, contact:

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